

O I P E J C 176
AUG 04 2003
PATENT & TRADEMARK OFFICE

TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
INVENTORS NAME: Krishna Seshan et al.
SERIAL NO.: 10/052089

1/4

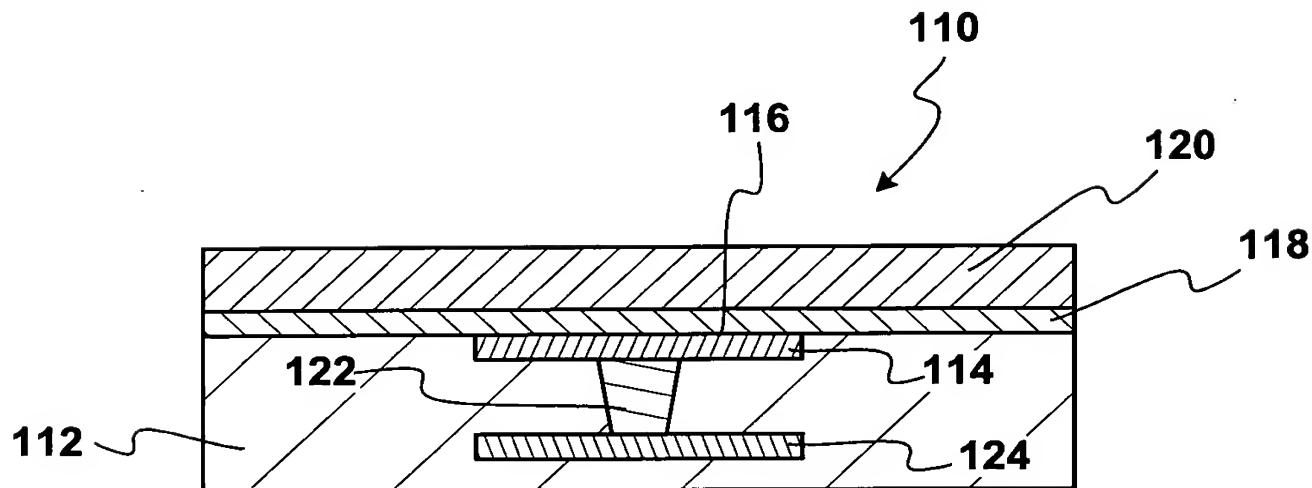


Fig. 1

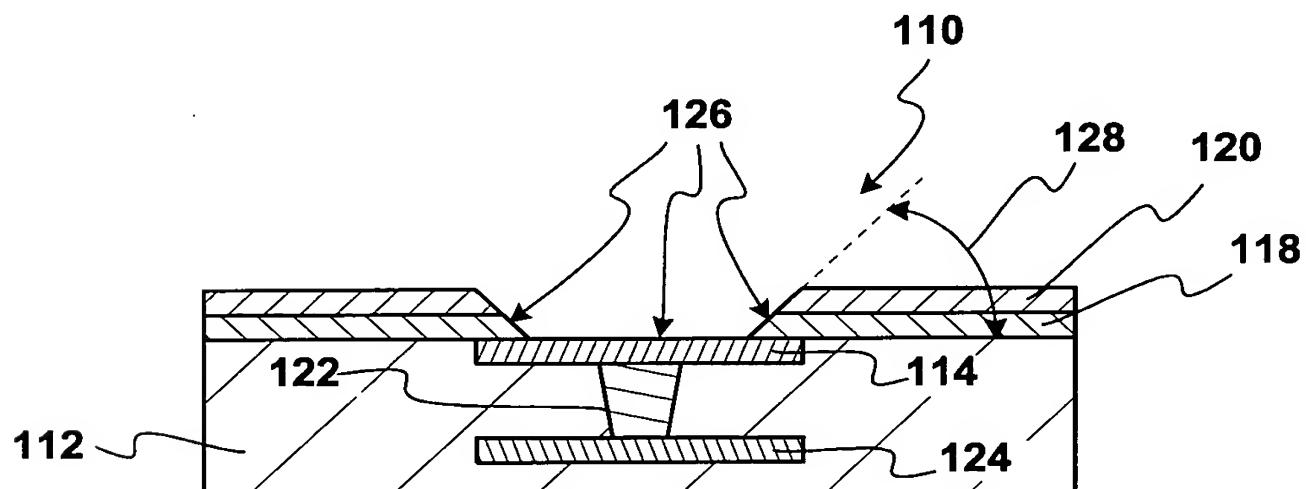


Fig. 2



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
INVENTORS NAME: Krishna Seshan et al.
SERIAL NO.: 10/052089

2/4

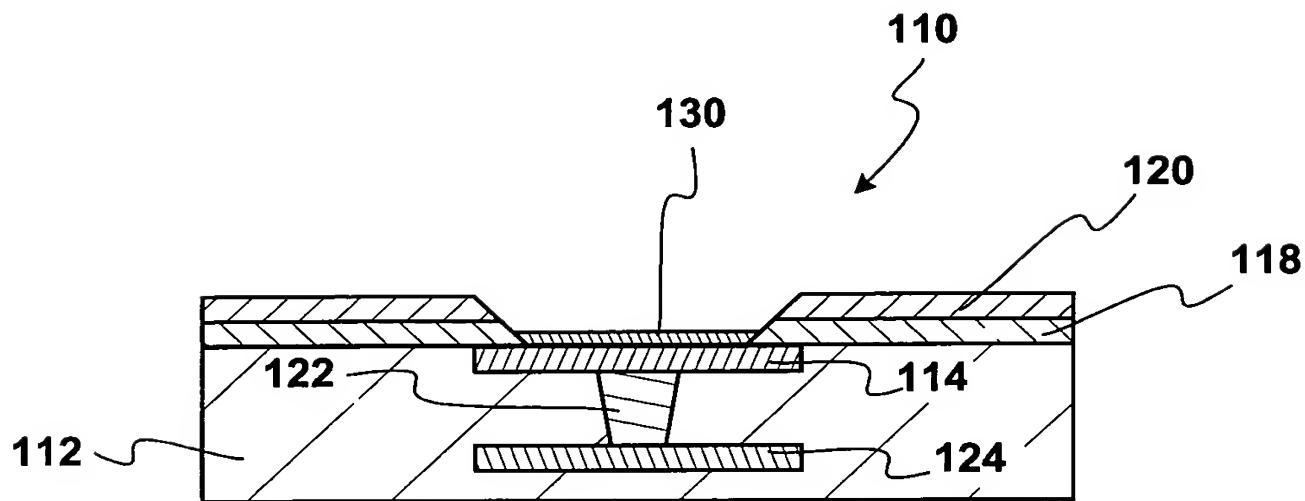


Fig. 3

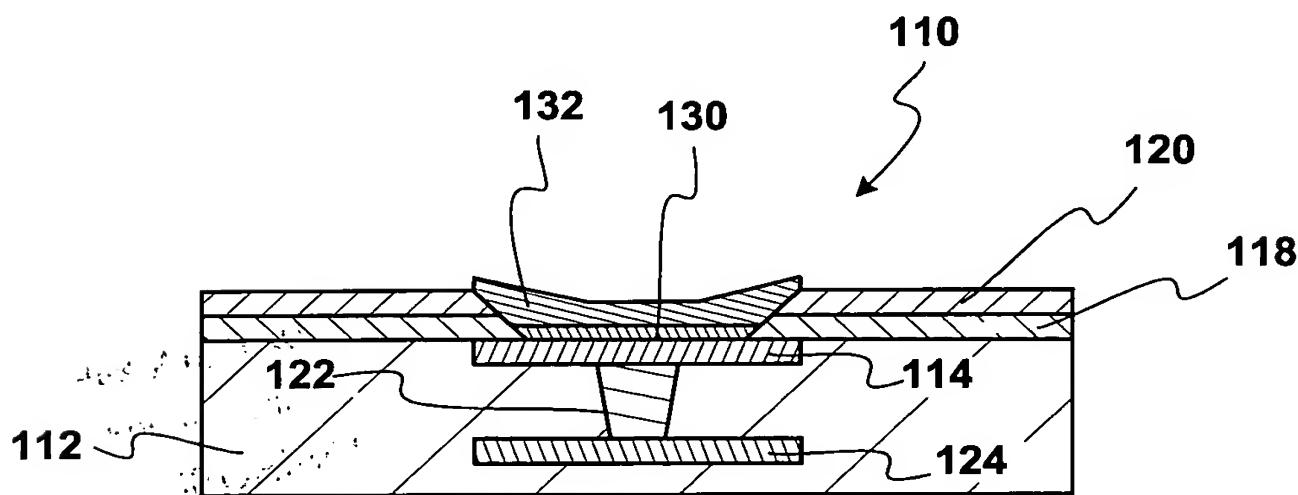


Fig. 4



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
INVENTORS NAME: Krishna Seshan et al.
SERIAL NO.: 10/052089

3/4

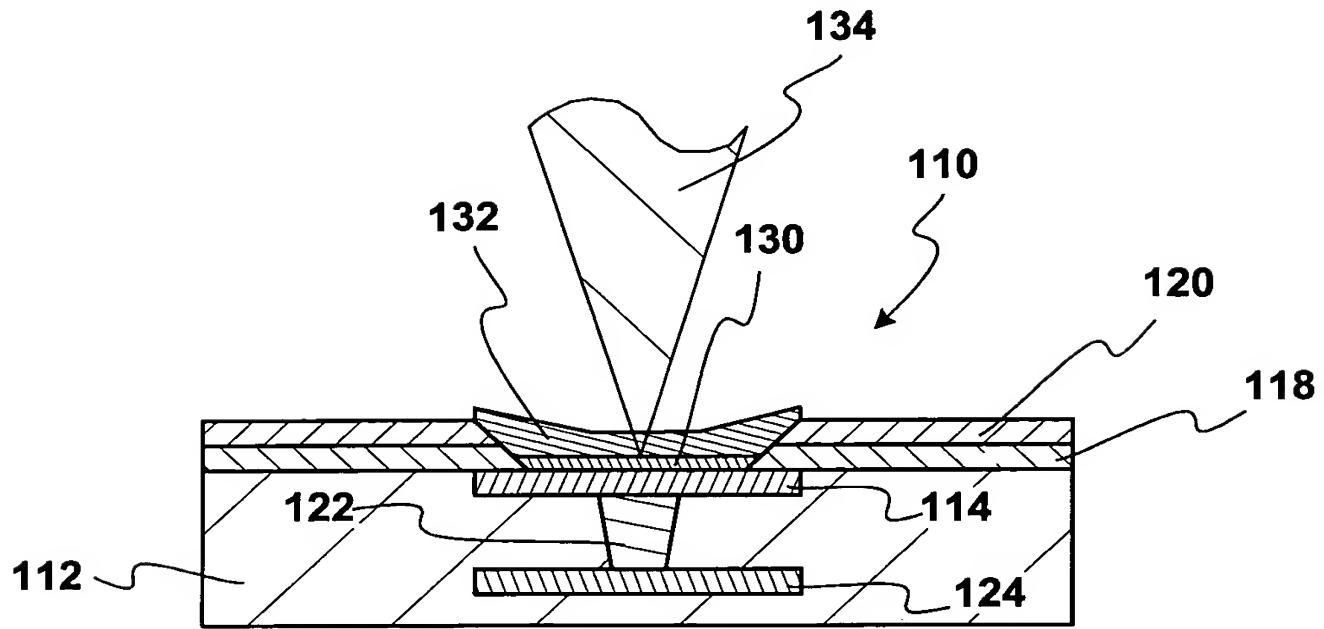


Fig. 5

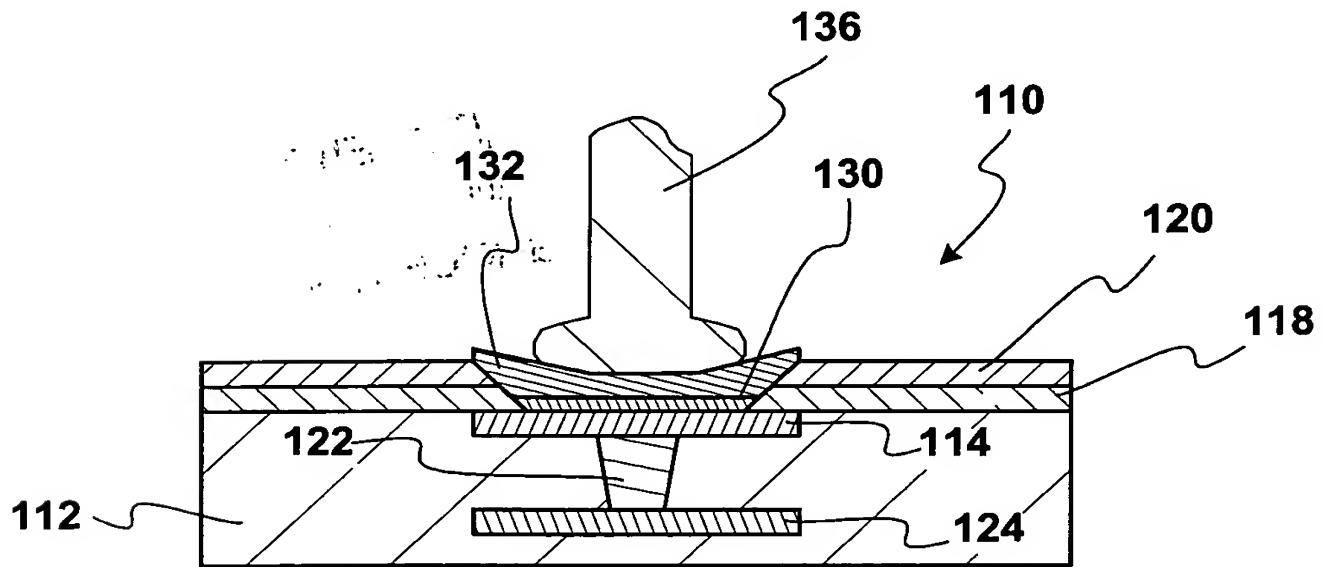


Fig. 6



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
INVENTORS NAME: Krishna Seshan et al.
SERIAL NO.: 10/052089

4/4

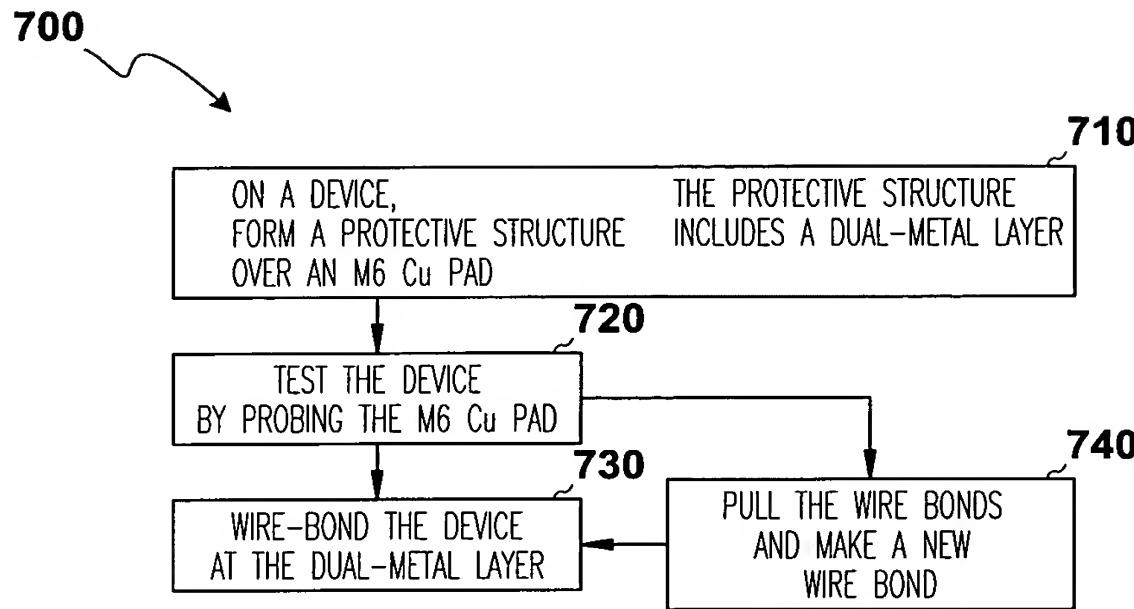


Fig. 7

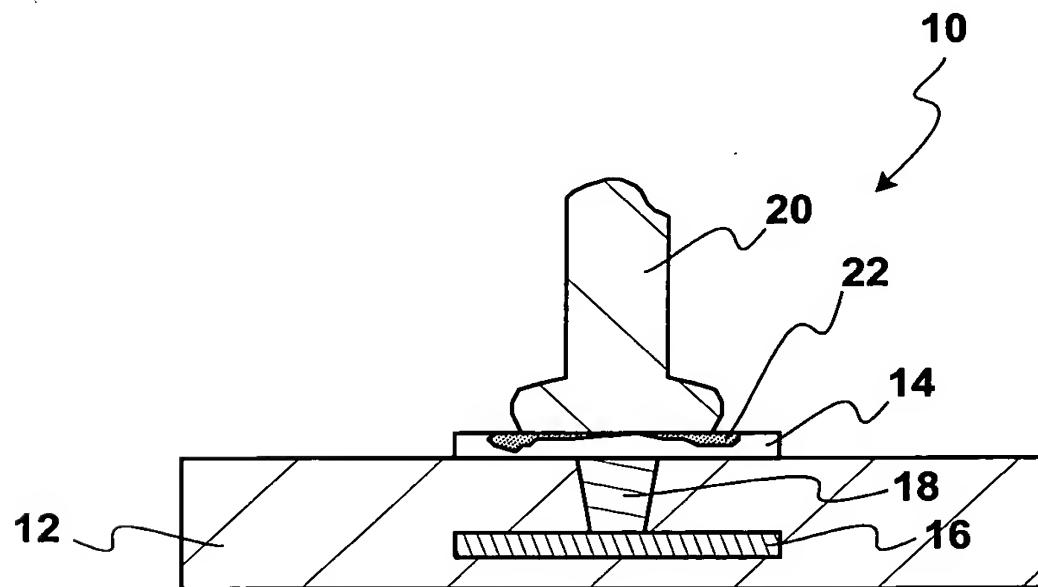


Fig. 8
(Prior Art)